

CLAIMS

1. A method for plating on at least one
conductive pattern on a surface of a substrate, said
substrate having at least a first surface and a second
5 surface, said method comprising the steps of:

placing the substrate on an electrode being
part of a plating holder such that said second surface of
said substrate is in contact with said electrode and said
conductive pattern is temporarily electrically connected to
10 said electrode; and

applying a plating solution on said first
surface of said substrate thereby inhibiting exposure of
said second surface to said plating solution.

characterised in that said electrode and said
15 conductive pattern are temporarily electrically connected
by forming a polysilicon or an amorphous silicon conductor
to temporarily connect said conductive pattern with a
contact to the substrate, said contact being formed on the
first surface of the substrate, and by providing an
20 electrical connection between said contact and said
electrode.

2. A method as recited in claim 1, wherein
said conductive pattern is positioned on a first die and
said contact is positioned on a second die different from
25 said first die.

3. A method as recited in claim 2, wherein
after said conductive pattern is plated, said method
further comprises the step of dicing the substrate

4. A method as in claim 1, wherein prior to
30 applying the plating solution, a resist layer is deposited
on said conductive pattern and patterned in order to create
at least one covered area and at least one uncovered area,
said uncovered area being exposable to said plating
solution.

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5. A method as recited in claim 1, where said plating solution comprises an element selected from a group comprising Ag, Cu, Au, Pt, Ti, Ni and Co.

6. A substrate having at least a first surface and a second surface opposite to said first surface, said first surface being exposable to a plating solution, said substrate comprising

a conductive pattern being positioned at said first surface of a substrate;

a contact to the first surface of the substrate; and

said conductive pattern being temporarily electrically connected by a polysilicon or an amorphous silicon conductor with said contact and said contact being electrically connected with said second surface.

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